



SPECIFICATION

• Supplier : Samsung electro-mechanics • Samsung P/N : CL31B223KCCNFNC

• Product : Multi-layer Ceramic Capacitor • Description : CAP, 22nF, 100V, ±10%, X7R, 1206

A. Samsung Part Number

<u>CL</u> <u>31</u> <u>B</u> <u>223</u> <u>K</u> <u>C</u> <u>C</u> <u>N</u> <u>F</u> <u>N</u> <u>C</u> ① ② ③ ④ ⑤ ⑥ ⑦ ⑧ ⑨ ⑩ ⑪

① Series	Samsung Multi-layer Ceramic Capacitor		
② Size	1206 (inch code)	L: 3.2 ± 0.15 mm	W: 1.6 ± 0.15 mm
③ Dielectric	X7R	Inner electrode	Ni
Capacitance	22 nF	Termination	Cu
⑤ Capacitance	±10 %	Plating	Sn 100% (Pb Free)
tolerance		Product	Product for POWER application
6 Rated Voltage	100 V	Special	Reserved for future use
7 Thickness	0.85 ± 0.15 mm	Packaging	Cardboard Type, 7" reel

B. Samsung Reliablility Test and Judgement condition

	Performance	Test condition	
Capacitance	Within specified tolerance	1klb±10% 1.0±0.2Vrms	
Tan δ (DF)	0.025 max.		
Insulation	10,000Mohm or 500Mohm⋅μF	Rated Voltage 60~120 sec.	
Resistance	Whichever is Smaller		
Appearance	No abnormal exterior appearance	Microscope (×10)	
Withstanding	No dielectric breakdown or	200% of the rated voltage	
Voltage	mechanical breakdown		
Temperature	X7R		
Characterisitcs	(From -55℃ to 125℃, Capacitance change shoud be within ±15%)		
Adhesive Strength	No peeling shall be occur on the	500g·F, for 10±1 sec.	
of Termination	terminal electrode		
Bending Strength	Capacitance change : within ±12.5%	Bending to the limit (1mm)	
		with 1.0mm/sec.	
Solderability	More than 75% of terminal surface	SnAg3.0Cu0.5 solder	
	is to be soldered newly	245±5℃, 3±0.3sec.	
		(preheating : 80~120 ℃ for 10~30sec.)	
Resistance to	Capacitance change : within ±7.5%	Solder pot : 270±5℃, 10±1sec.	
Soldering heat	Tan δ, IR : initial spec.		

	Performance	Test condition
Vibration Test	Capacitance change : within ±5%	Amplitude : 1.5mm
	Tan δ, IR : initial spec.	From 10Hz to 55Hz (return : 1min.)
		2hours × 3 direction (x, y, z)
Moisture	Capacitance change : within ±12.5%	With rated voltage
Resistance	Tan δ : 0.05 max	40±2℃, 90~95%RH, 500+12/-0hrs
	IR : 500Mohm or 25Mohm ⋅ μF	
	Whichever is Smaller	
High Temperature	Capacitance change : within ±12.5%	With 200% of the rated voltage
Resistance	Tan δ : 0.05 max	Max. operating temperature
	IR : 1000Mohm or 50Mohm ⋅ μF	
	Whichever is Smaller	1000+48/-0hrs
Temperature	Capacitance change : within ±7.5%	1 cycle condition
Cycling	Tan δ, IR : initial spec.	Min. operating temperature \rightarrow 25 $^{\circ}$ C
		$ ightarrow$ Max. operating temperature $ ightarrow$ 25 $^{\circ}\!$
		5 cycle test

C. Recommended Soldering method :

Reflow (Reflow Peak Temperature : 260+0/-5 $^{\circ}$ C, 10sec. Max)

^{*} For the more detail Specification, Please refer to the Samsung MLCC catalogue.